

231	1	saia-richard-joseph.in. and cavity and coat	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/22 19:00
232	35	saia-richard-joseph.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/22 19:01
233	0	Durocher-kevin-mathew.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/22 19:03
234	3	kapusta-christopher-james.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/22 19:02
235	6	nielsen-matthew-christian.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/22 19:03
236	29	Durocher-kevin-matthew.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/22 19:03

L Number	Hits	Search Text	DB	Time stamp
95	5	("5216278" "5216283" "5311060" "5442230" "5468999").PN.	USPAT	2003/07/22 15:04
218	307	(chip die IC) with direct with (heat adj (sink plate plug element spread\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/22 15:19
219	7	("5777386" "5818106" "5977626" "6163458" "6255143" "6285554" "6313528").PN.	USPAT	2003/07/22 15:21
220	3	("4692791" "5311059" "5371404").PN.	USPAT	2003/07/22 15:21
221	33	("5041902" "5131233" "5328870" "5355283" "5381042" "5455462" "5471011" "5478007" "5482898" "5485037" "5583378" "5629561" "5650593" "5701034" "5708567" "5722161" "5723899" "5729432" "5807768" "5852870" "5854511" "5854741" "5859475" "5866939" "5947193" "5985695" "6028354" "6117705" "6124637" "6150709" "6198163" "6222731" "6229204").PN.	USPAT	2003/07/22 15:22
222	2218	2577796,716-722.ccls. and (heat adj (sink plate plug element spread\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/22 16:27
223	52	Yasunaga-masatoshi.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/22 17:50
224	2	("4621304").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/22 18:32
225	1	("6499214").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/22 18:41
226	14697	coat\$4 with cavity	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/22 18:41
227	34	(protect\$4 adj coat\$4) near2 cavity	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/22 18:47
228	3231	coat\$4 near2 cavity	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/22 18:49
229	1449	coat\$4 near1 cavity	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/22 18:53
230	188	coat\$4 near1 cavity and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/22 18:59